AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

1. (Currently Amended) A smart label comprising a circuitry pattern and at least one capacitor plate on a smart label substrate, and a structural part comprising an integrated circuit on a chip and at least one capacitor plate on a structural part substrate, the structural part substarte being substantially smaller than the smart label substrate and being ~~the structural part~~ attached to the smart label substrate in such a manner that the capacitor plate on the smart label substrate and the capacitor plate on the structural part substrate are aligned thereby electrically connecting the circuitry pattern and the integrated circuit on the chip through a dielectric layer between the capacitor plates ~~and/or the circuitry pattern, and the circuitry pattern being electrically connected to the integrated circuit on the chip, wherein that the integrated circuit on the chip is connected to the circuitry pattern via at least one capacitor located outside the chip~~.

2. (Original) The smart label according to claim 1, wherein the integrated circuit on the chip is connected to the circuitry pattern via two capacitors connected in series and located outside the chip.

3. (Original) The smart label according to claim 1, wherein the structural part comprising the integrated circuit on the chip is attached to the smart label by means of a thermoplastic material.

4. (Original) The smart label according to claim 3, wherein the thermoplastic material is an anisotropic conductive thermoplastic film.

5. (Cancel)

6. (Currently Amended) The smart label according to claim 2 ~~5~~, wherein the smart label substrate has a dissipation factor of ~~the smart label substrate is~~ not more than 0.7×10^{-3}.

7. (Currently Amended) The smart label according to claims 1 ~~5~~ or 6, wherein the material of the smart label substrate is polyolefin~~, such as polypropylene or polyethylene~~.

8. (Currently Amended) The smart label according to claims ~~5~~ 1, wherein the structural part is attached to the smart label substrate on the side opposite to the side where the circuitry pattern is located, and the dielectric layer is the smart label substrate ~~thereby preventing shortcircuiting~~.

9. (Original) The smart label according to claim 3 or 8, wherein the integrated circuit on the chip is located between the thermoplastic material and the smart label substrate.

10. (Currently Amended) The smart label according to claim 1, wherein the material of the structural part substrate is selected from the group consisting of polyimide and ~~or~~ polyester.

11. (Currently Amended) A smart label web comprising smart labels one after another and/or side by side, the smart label comprising a circuitry pattern and at least one capacitor plate on a smart label substrate and a structural part comprising an integrated circuit on a chip ~~attached to it~~, and at least one capacitor plate on a structural part substrate, the structural part substrate being substantially smaller than the smart label substrate and being attached to the smart label substrate in such a manner that the capacitor plate on the smart label substrate and the capacitor plate on the structural part substrate are aligned thereby electrically connecting the circuitry pattern and ~~the integrated circuit on to the chip being attached to the smart label by means of a structural part separated from a separate carrier web, wherein~~ the integrated circuit on the chip through a dielectric layer between the capacitor plates ~~is connected to the circuitry pattern via at least one capacitor located outside the chip~~.

12. (Original) The smart label web according to claim 11, wherein the integrated circuit on the chip is connected to the circuitry pattern via two capacitors connected in series and located outside the chip.

13. (New) The smart label according to claim 1, wherein the structural part is attached to the smart label substrate on the same side where the circuitry pattern is located and the dielectric layer comprises a printed isolation layer.

14. (New) The smart label according to claim 7, wherein the polyolefin is selected from the group consisting of polypropylene and polyethylene.

15. (New) A smart label comprising a circuitry pattern on a smart label substrate; and

a structural part, the structural part comprising a thermoplastic film, a base web, and an integrated circuit on a chip on the thermoplastic film, the structural part being attached to the smart label substrate, and the circuitry pattern being electrically connected to the integrated circuit on the chip by at least one capacitor outside the chip, at least one capacitor plate of the at least one capacitor on the smart label substrate opposing at least one capacitor plate of the at least one capacitor on the surface of the base web of the structural part, at least one of the opposing plates being larger than its opposite plate, the structural part smaller than the smart label substrate.

16. (New) The smart label according to claim 15, wherein the integrated circuit on the chip is connected to the circuitry pattern via two capacitors connected in series and located outside the chip.

17. (New) The smart label according to claim 16, wherein the thermoplastic film material is an anisotropically conductive.

18. (New) The smart label according to claim 17, wherein the capacitor comprises capacitor plates which are formed on the smart label substrate and the structural part substrate,

the anisotropically conductive thermoplastic film on the same side of the smart label substrate where the circuitry pattern is located and is isolated from th circuitry patter, the smart label substrate forming a dielectric layer between the capacitor plates.

19. (New) The smart label according to claim 17, wherein the capacitor comprises capacitor plates which are formed on the smart label substrate and the structural part substrate, the smart label substrate forming a dielectric layer between the capacitor plates.

20. (New) The smart label according to claim 16, wherein the smart label substrate has a dissipation factor of not more than 0.7×10^{-3}.

21. (New) The smart label according to claims 16 or 20, wherein the material of the smart label substrate is polyolefin.

22. (New) The smart label according to claim 16, wherein the structural part is attached to the smart label substrate on the side opposite to the side where the circuitry pattern is located, and the dielectric layer is the smart label substrate.

23. (New) The smart label according to claims 16 or 22 wherein the structural part comprising the integrated circuit on the chip is attached to the smart label by the thermoplastic film.

24. (New) The smart label according to claim 23, wherein the integrated circuit on the chip is located between the thermoplastic material and the smart label substrate.

25. (New) The smart label according to claim 16, wherein the base web of the structural part comprises material selected from the group consisting of polyimide and polyester.